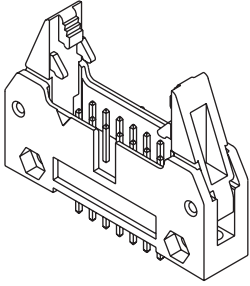


2.54mm (.100") Pitch QF-50™ Shrouded Header

5576 Vertical With Eject Levers



Features and Benefits

- 10 to 64 circuits
- Tin plated on solder tail
- Complies with industry standard DIN 41654
- Polarized
- Selective Gold plating options for contacts
- Eject levers allow end-to-end stacking with or without strain relief with no loss of board space

Reference Information

Packaging: Tray
Designed In: Millimeters
Mates With: 5320

Electrical

Voltage: 250V
Current: 1.0A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 500V
Insulation Resistance: 1000 Megohms min.

Physical

Housing: Glass-filled PBTP
Contact: Brass
Operating Temperature: -40 to +105°C

Circuits	Order No.			Lead-free
	Plating NBGS1	Plating NBGS2	Plating NBT2	
10	39-27-1103	39-27-1104	39-28-5105	Yes
14	39-27-1143	39-27-1144	39-28-5145	
16	39-27-1163	39-27-1164	39-28-5165	
20	39-27-1203	39-27-1204	39-28-5205	
26	39-27-1263	39-27-1264	39-28-5265	
30	39-27-1303	39-27-1304	39-28-5305	

Plating NBGS1: 39µ" (1µm) min. Nickel underplate. Contact area: 0.1µm min. Gold.

Solder area: 3µm min. Tin

Plating NBGS2: 39µ" (1µm) min. Nickel underplate. Contact area: 0.76µm min. Gold.

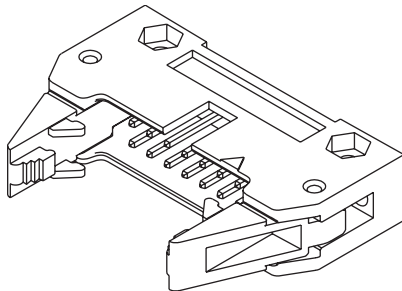
Solder area: 3µm min. Tin

Plating NBT2: 20µ" (0.5µm) min. Nickel underplate. Contact and solder area: 39µ" (1µm) min. Tin

Circuits	Order No.			Lead-free
	Plating NBGS1	Plating NBGS2	Plating NBT2	
34	39-27-1343	39-27-1344	39-28-5345	Yes
40	39-27-1403	39-27-1404	39-28-5405	
50	39-27-1503	39-27-1504	39-28-5505	
60	39-27-1603	39-27-1604		
64	39-27-1643	39-27-1644		

2.54mm (.100") Pitch QF-50™ Shrouded Header

5578 Right Angle With Eject Levers



Features and Benefits

- 10 to 64 circuits
- Tin plated on solder tail
- Complies with industry standard DIN 41654
- Polarized
- Selective Gold plating options for contacts
- Eject levers allow end-to-end stacking with or without strain relief with no loss of board space

Reference Information

Packaging: Tray
Mates With: 5320
Designed In: Millimeters

Electrical

Voltage: 250V
Current: 1.0A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 500V
Insulation Resistance: 1000 Megohms min.

Physical

Housing: Glass-filled PBTP
Contact: Brass
Operating Temperature: -40 to +105°C

Circuits	Order No.			Lead-free
	Plating NBGS17F	Plating NBGS2	Plating NBT2	
10	39-53-6108	39-53-6109	39-28-5106	Yes
14	39-53-6148	39-53-6149	39-28-5146	
16	39-53-6168	39-53-6169	39-28-5166	
20	39-53-6208	39-53-6209	39-28-5206	
26	39-53-6268	39-53-6269	39-28-5266	
30	39-53-6308	39-53-6309	39-28-5306	

Plating NBGS1: 39µ" (1µm) min. Nickel underplate. Contact area: 0.1µm min. Gold.

Solder area: 3µm min. Tin

Plating NBGS2: 39µ" (1µm) min. Nickel underplate. Contact area: 0.76µm min. Gold.

Solder area: 3µm min. Tin

Plating NBT2: 20µ" (0.5µm) min. Nickel underplate. Contact and solder area: 39µ" (1µm) min. Tin

Circuits	Order No.			Lead-free
	Plating NBGS17F	Plating NBGS2	Plating NBT2	
34	39-53-6348	39-53-6349	39-28-5346	Yes
40	39-53-6408	39-53-6409	39-28-5406	
50	39-53-6508	39-53-6509	39-28-5506	
60	39-53-6608	39-53-6609		
64	39-53-6648	39-53-6649		